



Solderability Profile

Nylon 6T Material Temperature Specifications

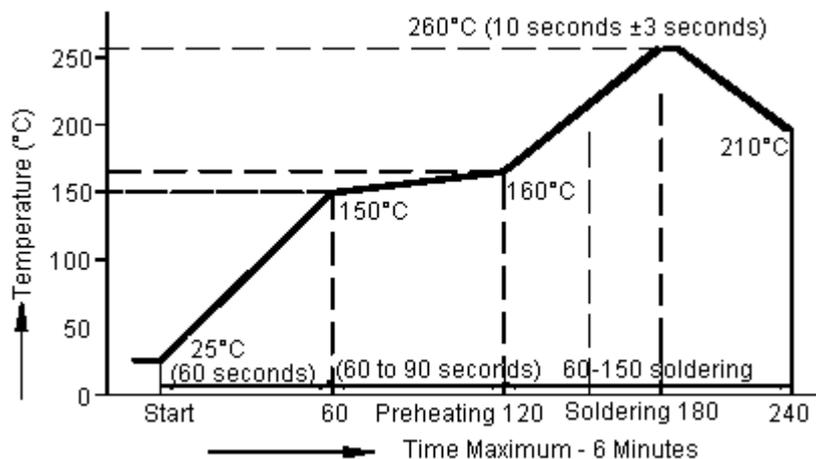
Solder regular conditions:

Soldering temperature : 260°C ±5°C.
 Time : 10 seconds ±3 seconds.
 Minimum solder wetting percentage : 95%.

Multicomp test conditions:

1. Solder method : Reflow or wave-soldering.
2. Environment : Room air.
3. Solder composition : Soldering paste.
4. Test board : 52mm x 36.5mm x 1.6mm thick.
5. This temperature profile is based on the above conditions. In individual applications the actual temperature may vary. Consult solder paste and equipment manufacturer for specific recommendations.
6. There must not be visible defect after testing.

Reflow Condition



Nylon 6T Recommended Temperature Profile

Part Number Table

Description	Part Number
Header, Right Angle, SMT, 2 Way	2261(5561)R-02T-SM1

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